

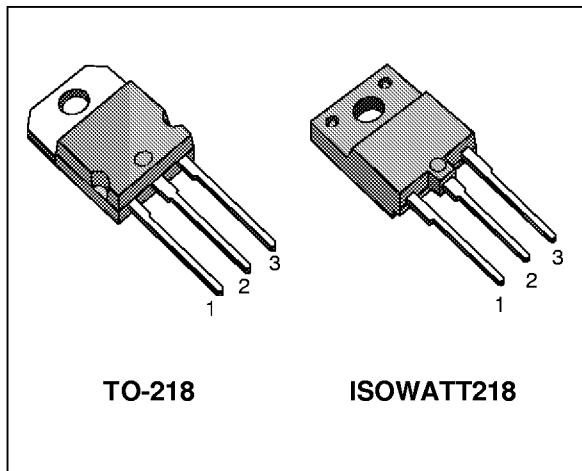
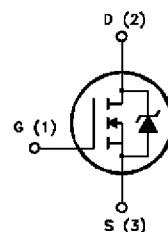
N - CHANNEL ENHANCEMENT MODE  
 POWER MOS TRANSISTOR

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STHV102	1000 V	< 3.5 Ω	4.2 A
STHV102FI	1000 V	< 3.5 Ω	2.6 A

- TYPICAL R<sub>DS(on)</sub> = 3.1 Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- LOW INPUT CAPACITANCE
- LOW GATE CHARGE
- APPLICATION ORIENTED CHARACTERIZATION

**APPLICATIONS**

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- CONSUMER AND INDUSTRIAL LIGHTING
- DC-AC INVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLY (UPS)


**INTERNAL SCHEMATIC DIAGRAM**

**ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value		Unit
		STHV102	STHV102FI	
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	1000	1000	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	1000	1000	V
V <sub>GS</sub>	Gate-source Voltage	± 20	± 20	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>c</sub> = 25 °C	4.2	2.6	A
I <sub>D</sub>	Drain Current (continuous) at T <sub>c</sub> = 100 °C	2.6	1.6	A
I <sub>DM(•)</sub>	Drain Current (pulsed)	16	16	A
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	150	60	W
	Derating Factor	1.2	0.48	W/°C
V <sub>ISO</sub>	Insulation Withstand Voltage (DC)	—	4000	V
T <sub>stg</sub>	Storage Temperature	-65 to 150		°C
T <sub>j</sub>	Max. Operating Junction Temperature	150		°C

(•) Pulse width limited by safe operating area

## THERMAL DATA

		TO-218	ISOWATT218	
R <sub>thj-case</sub>	Thermal Resistance Junction-case	Max	0.83	2.08 °C/W
R <sub>thj-amb</sub> R <sub>thc-sink</sub>	Thermal Resistance Junction-ambient Thermal Resistance Case-sink	Max Typ	30 0.1 300	°C/W °C/W °C
T <sub>I</sub>	Maximum Lead Temperature For Soldering Purpose			

## AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T <sub>j</sub> max, δ < 1%)	4.2	A
E <sub>AS</sub>	Single Pulse Avalanche Energy (starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 25 V)	180	mJ
E <sub>AR</sub>	Repetitive Avalanche Energy (pulse width limited by T <sub>j</sub> max, δ < 1%)	9.2	mJ
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (T <sub>c</sub> = 100 °C, pulse width limited by T <sub>j</sub> max, δ < 1%)	2.5	A

ELECTRICAL CHARACTERISTICS (T<sub>case</sub> = 25 °C unless otherwise specified)

## OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 μA V <sub>GS</sub> = 0	1000			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating × 0.8 T <sub>c</sub> = 125 °C			25 250	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 20 V			± 100	nA

## ON (\*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>G(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> I <sub>D</sub> = 250 μA	2	3	4	V
R <sub>D(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V I <sub>D</sub> = 2 A		3.1	3.5	Ω
I <sub>D(on)</sub>	On State Drain Current	V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>D(on)max</sub> V <sub>GS</sub> = 10 V	4.2			A

## DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>D(on)max</sub> I <sub>D</sub> = 2 A	2	4		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V <sub>DS</sub> = 25 V f = 1 MHz V <sub>GS</sub> = 0		1230 165 70	1500 200 85	pF pF pF

## ELECTRICAL CHARACTERISTICS (continued)

### SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$	Turn-on Time Rise Time	$V_{DD} = 800 \text{ V}$ $I_D = 2 \text{ A}$ $R_G = 50 \Omega$ $V_{GS} = 10 \text{ V}$ (see test circuit, figure 3)		36 130	45 165	ns ns
$(di/dt)_{on}$	Turn-on Current Slope	$V_{DD} = 800 \text{ V}$ $I_D = 4 \text{ A}$ $R_G = 50 \Omega$ $V_{GS} = 10 \text{ V}$ (see test circuit, figure 5)		180		$\text{A}/\mu\text{s}$
$Q_g$ $Q_{gs}$ $Q_{gd}$	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 800 \text{ V}$ $I_D = 4 \text{ A}$ $V_{GS} = 10 \text{ V}$		80 8 40	100	nC nC nC

### SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(Voff)}$ $t_f$ $t_c$	Off-voltage Rise Time Fall Time Cross-over Time	$V_{DD} = 800 \text{ V}$ $I_D = 4 \text{ A}$ $R_G = 50 \Omega$ $V_{GS} = 10 \text{ V}$ (see test circuit, figure 5)		100 25 155	125 32 190	ns ns ns

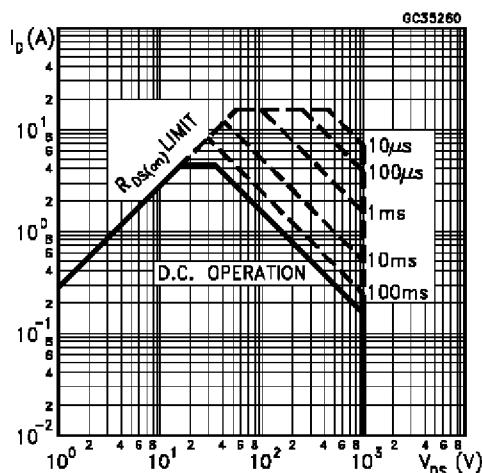
### SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{SD}$ $I_{SDM}(\bullet)$	Source-drain Current Source-drain Current (pulsed)				4.2 16	A A
$V_{SD} (\ast)$	Forward On Voltage	$I_{SD} = 4.2 \text{ A}$ $V_{GS} = 0$			2	V
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 4.2 \text{ A}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 100 \text{ V}$ $T_j = 150^\circ\text{C}$ (see test circuit, figure 5)		1200 30 50		ns $\mu\text{C}$ A

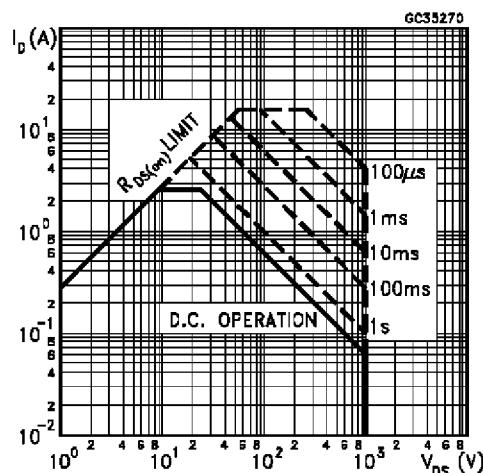
(\*) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %

(•) Pulse width limited by safe operating area

### Safe Operating Areas For TO-218

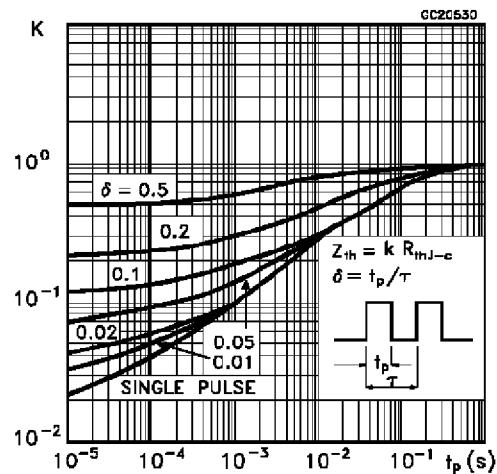


### Safe Operating Areas For ISOWATT218

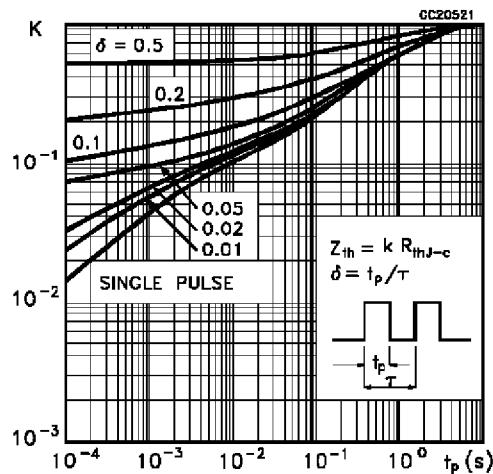


## STHV102/F1

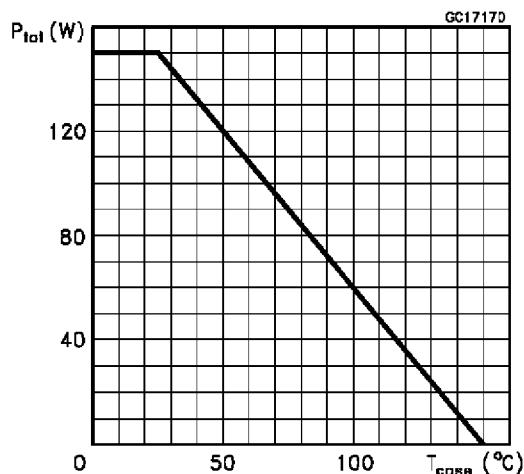
Thermal Impedance For TO-218



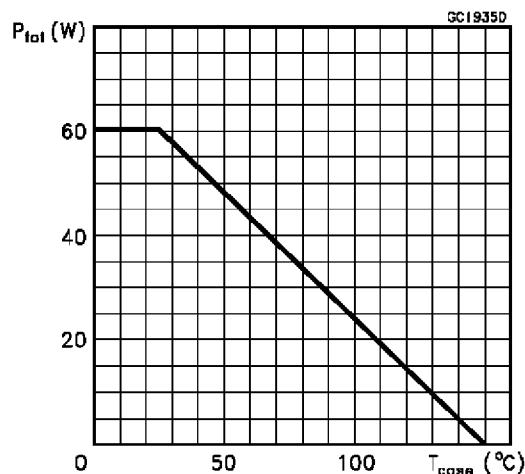
Thermal Impedance For ISOWATT218



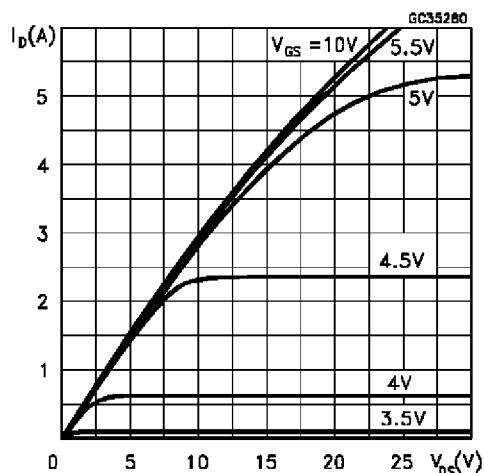
Derating Curve For TO-218



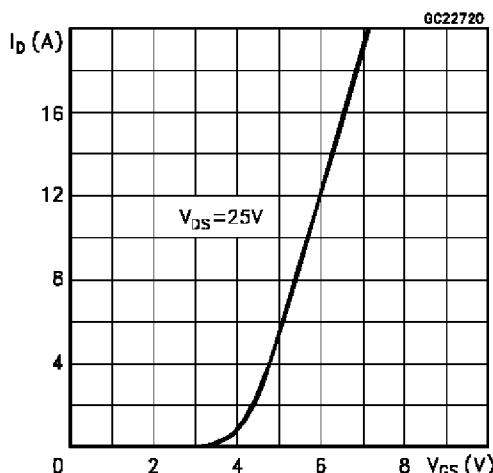
Derating Curve For ISOWATT218



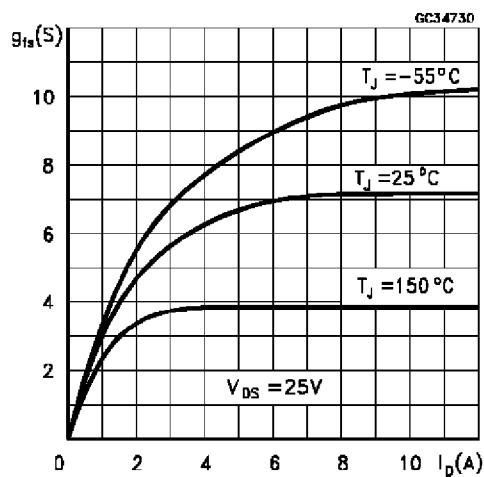
Output Characteristics



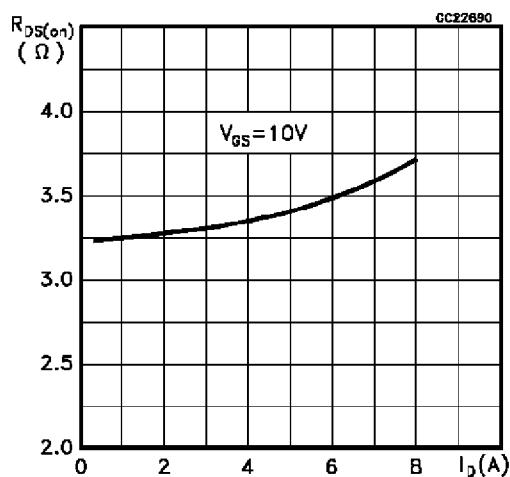
Transfer Characteristics



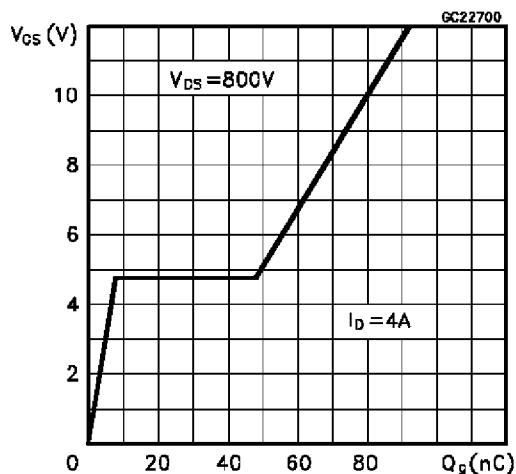
Transconductance



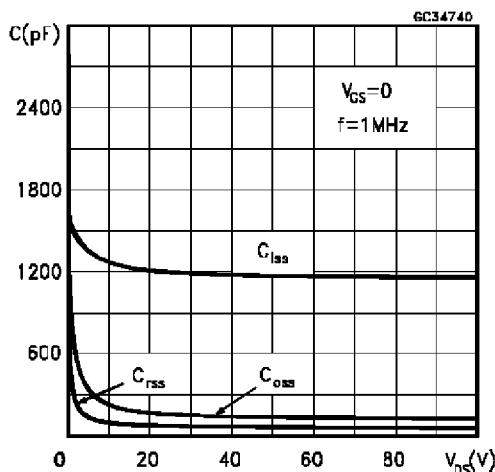
Static Drain-source On Resistance



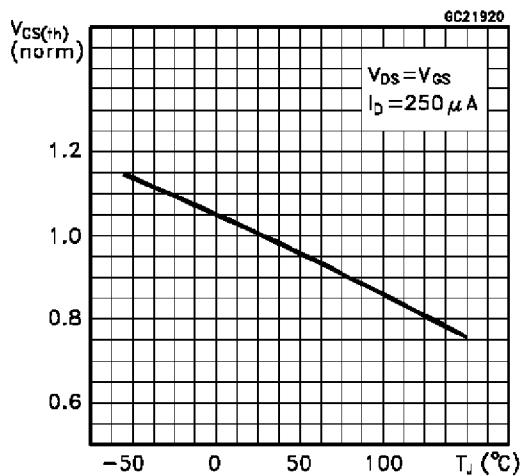
Gate Charge vs Gate-source Voltage



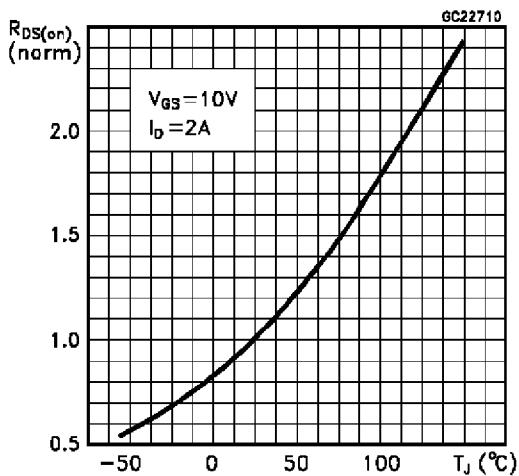
Capacitance Variations



Normalized Gate Threshold Voltage vs Temperature

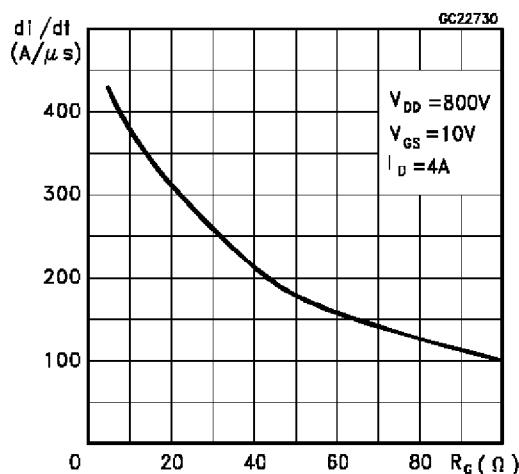


Normalized On Resistance vs Temperature

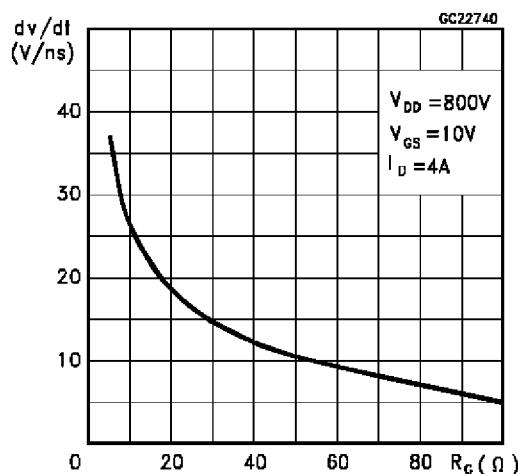


## STHV102/FI

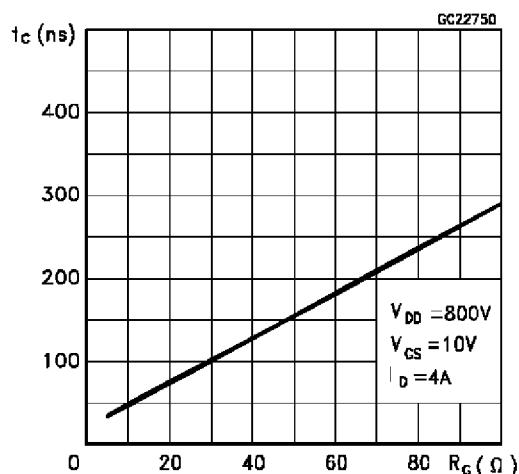
Turn-on Current Slope



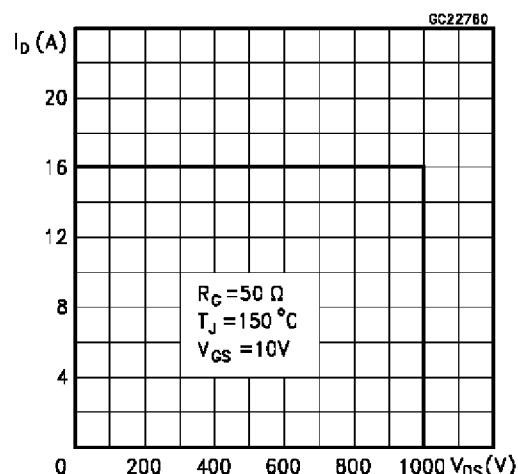
Turn-off Drain-source Voltage Slope



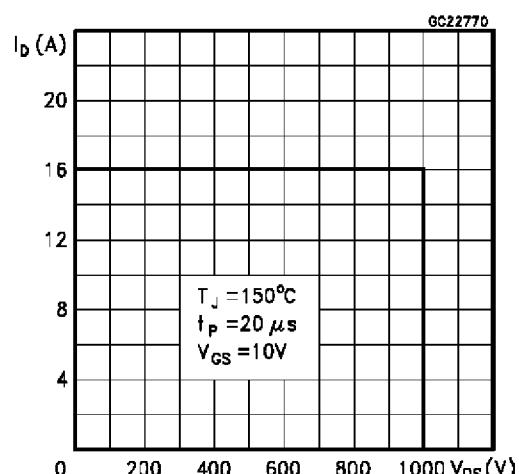
Cross-over Time



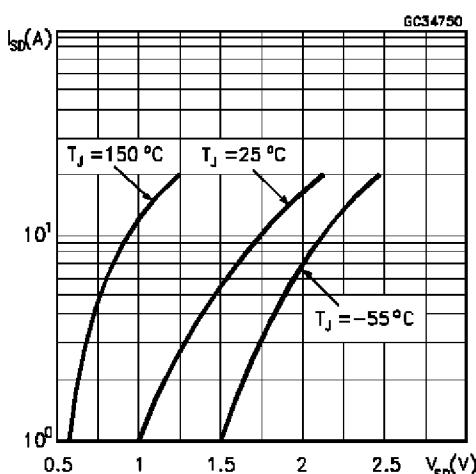
Switching Safe Operating Area

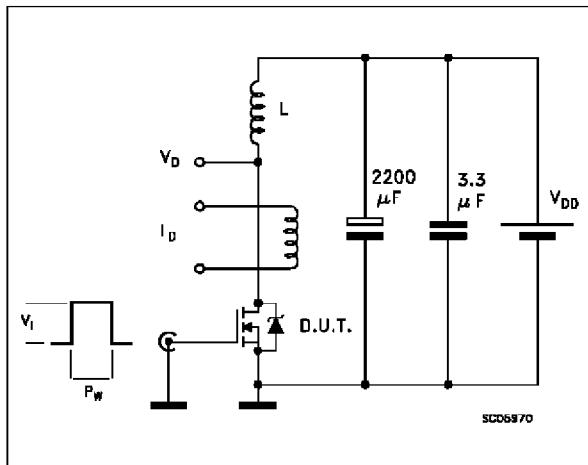
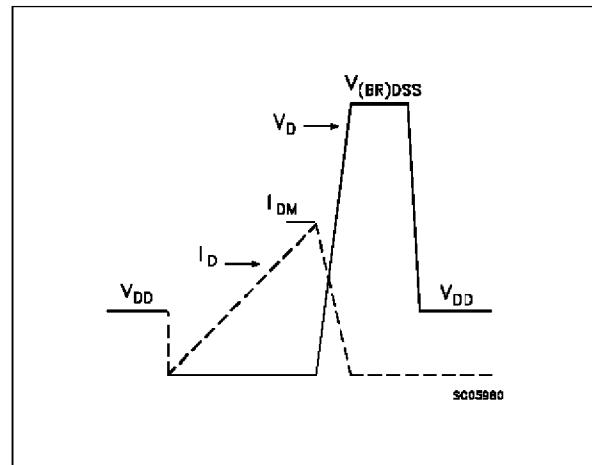
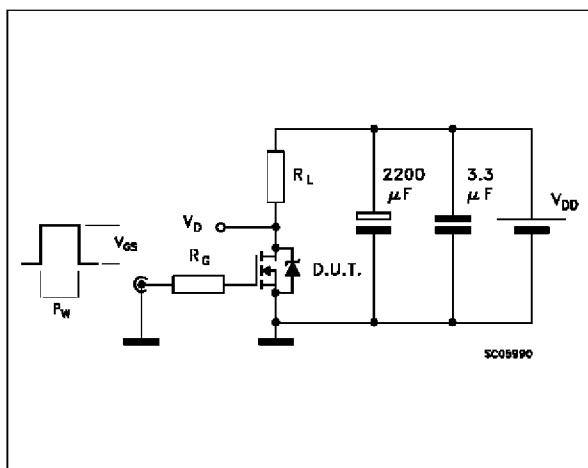
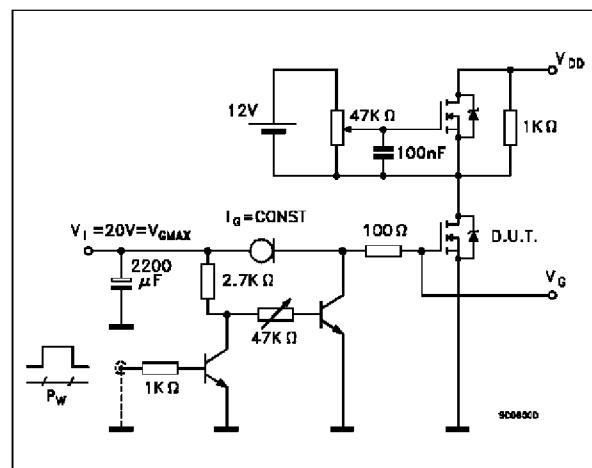
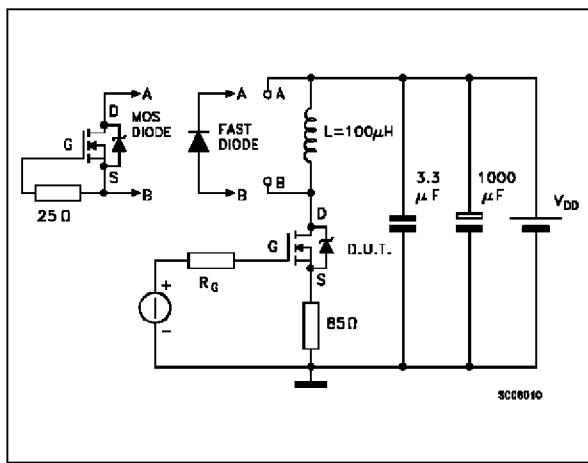


Accidental Overload Area



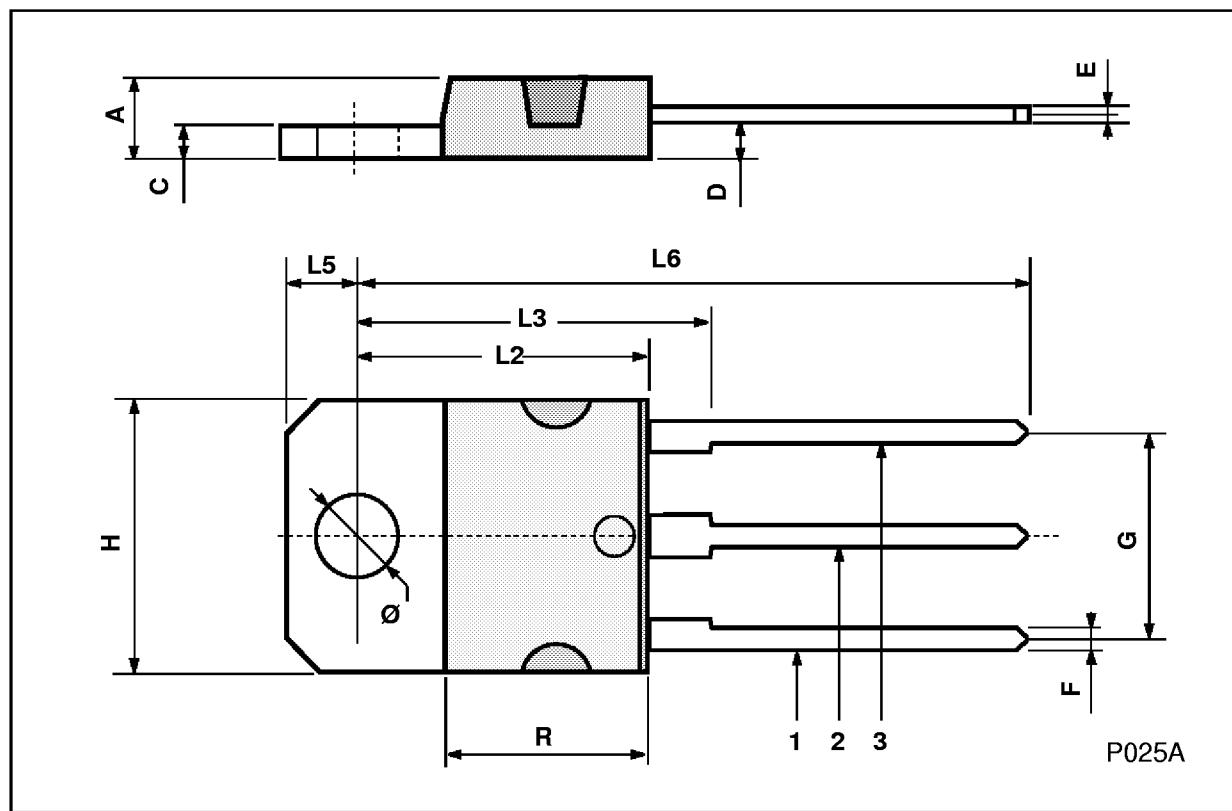
Source-drain Diode Forward Characteristics



**Fig. 1:** Unclamped Inductive Load Test Circuits**Fig. 2:** Unclamped Inductive Waveforms**Fig. 3:** Switching Times Test Circuits For Resistive Load**Fig. 4:** Gate Charge Test Circuit**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Reverse Recovery Time

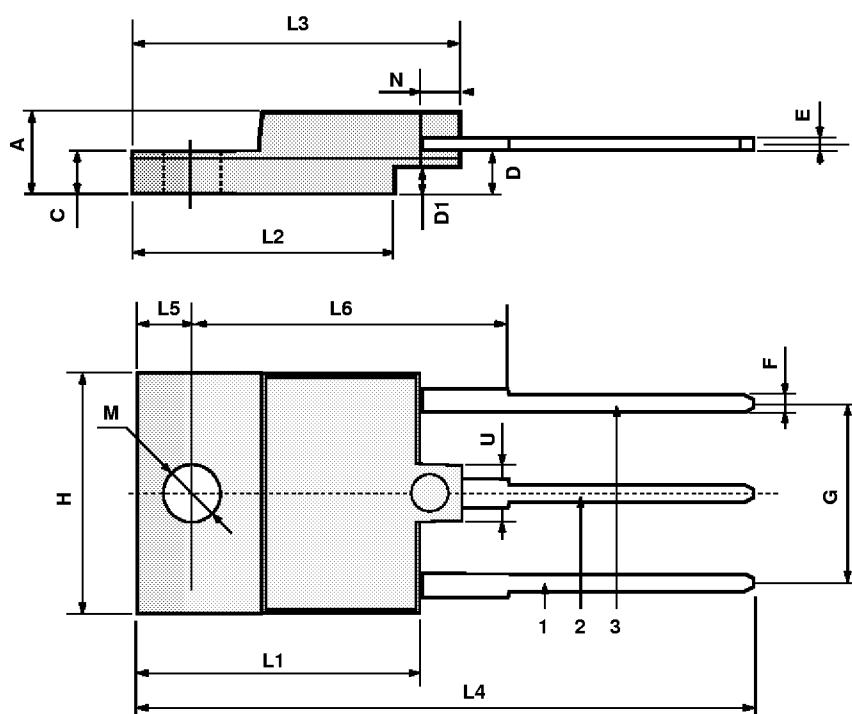
## TO-218 (SOT-93) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.7		4.9	0.185		0.193
C	1.17		1.37	0.046		0.054
D		2.5			0.098	
E	0.5		0.78	0.019		0.030
F	1.1		1.3	0.043		0.051
G	10.8		11.1	0.425		0.437
H	14.7		15.2	0.578		0.598
L2	—		16.2	—		0.637
L3		18			0.708	
L5	3.95		4.15	0.155		0.163
L6		31			1.220	
R	—		12.2	—		0.480
Ø	4		4.1	0.157		0.161



## ISOWATT218 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	5.35		5.65	0.210		0.222
C	3.3		3.8	0.130		0.149
D	2.9		3.1	0.114		0.122
D1	1.88		2.08	0.074		0.081
E	0.45		1	0.017		0.039
F	1.05		1.25	0.041		0.049
G	10.8		11.2	0.425		0.441
H	15.8		16.2	0.622		0.637
L1	20.8		21.2	0.818		0.834
L2	19.1		19.9	0.752		0.783
L3	22.8		23.6	0.897		0.929
L4	40.5		42.5	1.594		1.673
L5	4.85		5.25	0.190		0.206
L6	20.25		20.75	0.797		0.817
M	3.5		3.7	0.137		0.145
N	2.1		2.3	0.082		0.090
U		4.6			0.181	



P025C